

Title (en)

METHOD FOR PRINTING A STRUCTURED SILVER COATING WITH IMPROVED CURRENT CONDUCTIVITY

Title (de)

VERFAHREN ZUM DRUCKEN EINER STRUKTURIERTEN SILBERBESCHICHTUNG MIT VERBESSERTER STROMTRAGFÄHIGKEIT

Title (fr)

PROCÉDÉ D'IMPRESSION D'UN REVÊTEMENT EN ARGENT STRUCTURÉ À INTENSITÉ MAXIMALE ADMISSIBLE AMÉLIORÉE

Publication

**EP 3785489 B1 20230802 (DE)**

Application

**EP 19714224 A 20190404**

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Abstract (en)

[origin: WO2019206592A1] The invention relates to a method for producing a silver coating on a glass panel (16), wherein the silver coating comprises at least one bus bar (1) and/or at least one solder contact surface, wherein the method comprises the steps of printing the silver coating onto the glass panel (16) by means of screenprinting with a printing pattern having printing and non-printing regions, and baking the printed silver coating, wherein the (printing region 12) of the printing pattern for the bus bar and/or the printing region of the printing pattern for the solder contact surface is at least partly provided with a dot matrix (14) or a line matrix (20). By means of the method according to the invention, higher printing thicknesses of the bus bars and/or solder contact surfaces can be achieved as compared with conventional methods without the use of a dot matrix.

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